DESCRIPTION

TITLE OF THE INVENTION: SEALING SHEET, METHOD FOR MANUFACTURING SEALING SHEET, AND METHOD FOR MANUFACTURING ELECTRONIC COMPONENT PACKAGE

TECHNICAL FIELD

[0001]

The present invention relates to a sealing sheet, a method for manufacturing the sealing sheet, and a method for manufacturing an electronic component package.

BACKGROUND ART

[0002]

For production of an electronic component package for a semiconductor or the like, typically a procedure is employed in which one or more electronic components fixed to a substrate, a temporary fixing material or the like are sealed with a sealing resin, and the sealed product is diced as necessary so that a package is formed per each electronic component. A sheet-shaped sealing resin having good handling ability is used as the sealing resin. A technique of blending a sheet for sealing with a filler by kneading is proposed as a method for increasing the blending amount of a filler for an improvement in the performance of a sealing sheet (Patent Document 1).

[0061]

In this embodiment, by employing the sealing sheet 11, the SAW chips 13 can be embedded and covered merely by bonding the sealing sheet 11 onto the printed wiring substrate 12, so that the production efficiency of the semiconductor package can be improved. In this case, the sealing sheet 11 can be laminated on the printed wiring substrate 12 by a known method such as heat pressing or a laminator. For heat pressing conditions, the temperature is, for example, 40 to 100°C, preferably 50 to 90°C, the pressure is, for example, 0.1 to 10 MPa, preferably 0.5 to 8 MPa, and the time is, for example, 0.3 to 10 minutes, preferably 0.5 to 5 minutes. When considering the adhesion and followability of the sealing sheet 11 to the SAW chips 13 and the printed wiring substrate 12, it is preferred to perform pressing preferably under a reduced pressure condition (e.g., 0.1 to 5 kPa).

[0062]

Since the minute domains of the elastomer are dispersed in the sealing sheet 11, the infiltration of the resin component to the hollow portion 14 is suppressed, and the operation reliability and connection reliability of the SAW chip ~~14~~ 13 can be improved.

[0063]

(Sealed body forming step)

In a sealed body forming step, the sealing sheet is